



Material Content Data Sheet



Sales Product Name		IPS80R900P7		Issued		1. August 2018		
MA#		MA002116524						
Package		PG-TO251-3-344		Weight*		339.23 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.033	0.60	0.60	5993	5993
leadframe	inorganic material	phosphorus	7723-14-0	0.046	0.01		136	
	non noble metal	iron	7439-89-6	0.154	0.05		455	
	non noble metal	copper	7440-50-8	154.154	45.44	45.50	454419	455010
	non noble metal	aluminium	7429-90-5	0.470	0.14	0.14	1386	1386
wire	non noble metal	aluminium	7429-90-5	0.470	0.14	0.14	1386	1386
encapsulation	organic material	carbon black	1333-86-4	0.443	0.13		1307	
	plastics	epoxy resin	-	13.449	3.96		39647	
	inorganic material	silicondioxide	60676-86-0	133.903	39.47	43.56	394724	435678
leadfinish	non noble metal	tin	7440-31-5	8.284	2.44	2.44	24420	24420
plating	non noble metal	nickel	7440-02-0	1.213	0.36	0.36	3577	3577
solder	non noble metal	tin	7440-31-5	0.044	0.01		129	
	noble metal	silver	7440-22-4	0.055	0.02		161	
	non noble metal	lead	7439-92-1	2.086	0.62	0.65	6150	6440
heatspreader	inorganic material	phosphorus	7723-14-0	0.007	0.00		20	
	non noble metal	iron	7439-89-6	0.023	0.01		68	
	non noble metal	copper	7440-50-8	22.867	6.74	6.75	67408	67496
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com